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HITD

U11

97-313732/29

*JP 09092775-A

U11 - 97-313732/29
HTD
semi conductor device with lead frame for high density mounting - has outer lead exposed

sealing resin surface

III FAC II CABLE LTD 95.09.22 95JP-244204

(97.04.04) 1101L 23/50

The device includes a semi conductor chip (1) bonded with a lead frame (4). The lead frame consists of an inner lead (4a) and an outer lead (4b).

A bonding wire (9) is used to bond the inner lead frame and the semi conductor chip. A mould resin (8) is sealed on the surface of the semi conductor chip. The main body has outer lead exposed in a sealing resin surface (8a).

ADVANTAGE - Decreases package thickness. Prevents semi conductor chip from damage. (Spp Dwg.No.2/7)

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